DFD6361 Operation (Half-cut Specification) (Rev. 1.00)

Trainee		Period	
Company		Trainer	

<DFD6361 Operation (Rev. 2.00)>

Item	Date	Trainee	Trainer
Day 1			
1. Machine Components			
1.1. Identify the Machine Sectional Composition			
1.2. Interpret the Operation Panel Screen Constituents			
1.3. Interpret the Software Keyboard			
2. Important Safety Information			
2.1. Interpret the Precautions on Safe Use of this Machine			
2.2. Interpret the Precautions on Safe Operation of this Machine			
2.3. Interpret the Safety Labels			
2.4. Interpret the EMO Switch			
2.5. Interpret the Interlock Mechanism			
2.6. Interpret the Interlock Mechanism of the Splash Cover/Arm Section Cover			
3. Start-up and Termination of the Machine			
3.1. Start up the Machine			
3.2. Execute the System Initialize			
3.3. Execute the Warming up			
3.4. Execute the Setup			
3.5. Terminate the Machine			
4. Full Automation Operation			
4.1. Interpret the Workpiece Process Flow during Full Automation			
4.2. Set the Cassette			
4.3. Operate the Device Data Operation Screens			
4.4. Interpret the Precautions and the Operation Flow of Full Automation			
4.5. Verify the Device Data			
4.6. Execute the Single Device Full Automation			
4.7. Resume the Cutting Operation after Aborting Full Automation			
4.8. Execute the Multiple Device Full Automation			
4.9. Interpret the Inspection Function			
4.10. Execute the Auto Inspection			-

Training Sign-off Sheet

4.11. Execute the Designated Inspection	 	
4.12. Remove the Workpiece under Inspection	 	
5. Making Corrections during Full Automation Operation		
5.1. Interpret the Correctable Items during Full Automation	 	
5.2. Adjust the Light Intensity and Microscope Focus	 	
5.3. Correct the Hairline Alignment	 	
5.4. Correct the Cutting Position	 	
5.5. Change the Feed Speed	 	
5.6. Correct the Blade Height	 	
6. Manual Operation		
6.1. Interpret the Operation Modes and Each Function	 	
6.2. Interpret the Outline of Manual Workpiece Transfer	 	
6.3. Execute the Loading	 	
6.4. Move the Workpiece from Chuck Table to Spinner Table	 	
6.5. Execute the Cleaning	 	
6.6. Execute the Unloading	 	
6.7. Unload All Workpieces	 	
6.8. Execute the Manual Alignment	 	
6.9. Execute the Auto Alignment	 	
6.10. Execute the Auto Cut	 	
6.11. Execute the Semi-auto Cut	 	
Day 2	 	
7. Device Data		
7.1. Copy the Device Data	 	
7.2. Move the Device Data	 	
7.3. Rename the Device Data	 	
7.4. Delete the Device Data	 	
7.5. Create the Device Data	 	
7.6. Interpret the Detail of Cutting Function	 	
7.7. Set the Process Control Table	 	
7.8. Interpret the Alignment Data	 	
7.9. Interpret the Cleaning Data	 	
7.10. Interpret the Water Program Maintenance Function Setting	 	
7.11. Interpret the Auto-down Function	 	
7.12. Set the Auto-setup Data	 	
7.13. Interpret the Purpose and the Data Setting for Precut Function	 	
7.14. Interpret the Kerf Check Function	 	
7.15. Set the Data of Kerf Check Function	 	
7.16. Interpret the Usage of Sub Index Data	 	
7.17. Edit the Device Data for Multiple Index Workpiece	 	



Training Sign-off Sheet

8. Blade Maintenance		
8.1. Interpret the Operation Flow of Blade Maintenance	 	
8.2. Replace the Hub Type Blade	 	
8.3. Replace the Washer Type Blade	 	
8.4. Set the Data for a New Blade	 	
8.5. Interpret the Data Setting of Used Blade Function	 	
8.6. Use the Used Blade Function	 	
8.7. Adjust the Blade Breakage Detector	 	
8.8. Interpret the Setup Function	 	
8.9. Set the Setup Data	 	
8.10. Execute the Contact Setup	 	
8.11. Execute the Non-contact Setup	 	
8.12. Execute the Sensor Calibration Setup	 	
8.13. Execute the Dress Cutting	 	
8.14. Correct the Hairline Alignment	 	
Day 3		
9. Alignment Teach		
9.1. Use the Measure Function	 	
9.2. Execute the Alignment Teach		
9.3. Interpret a Summary of the Alignment Target Selection	 	
9.4. Execute the Process Control Table Running (Except for Cutting)	 	
10. Error Recovery		
10.1. Interpret the Recovery Operations for Kerf Check Related Errors	 	
10.2. Interpret the Recovery Operations for Auto Alignment Related Errors	 	
10.3. Remove the Workpiece from the Chuck Table by Hand	 	
10.4. Remove the Workpiece from the Spinner Table by Hand	 	
10.5. Place the Workpiece on the Chuck Table by Hand	 	
10.6. Interpret the Recovery Operations for Manual Setup Related Errors	 	
10.7. Interpret the Recovery Operations for Auto Setup Related Errors		

<DFD6361 Operation (Half-cut Specification) (Rev. 2.00)>

1.1. Set the Cassette [Half-cut Specification] 1.2. Execute the Single Device Full Automation [Half-cut Specification] 1.3. Resume the Cutting Operation after Aborting Full Automation [Half-cut Specification] 1.4. Execute the Multiple Device Full Automation [Half-cut Specification] 2. Making Corrections during Full Automation Operation [Half-cut Specification] 2.1. Interpret the Correctable Items during Full Automation [Half-cut Specification] 2.2. Adjust the Light Intensity and Microscope Focus [Half-cut Specification] 2.3. Correct the Hairline Alignment [Half-cut Specification] 2.4. Correct the Cutting Position [Half-cut Specification] 2.5. Change the Feed Speed [Half-cut Specification] 2.6. Correct the Cutting Depth [Half-cut Specification] 3.1. Interpret the Difference between Cut Depth and Blade Height [Half-cut Specification] 3.2. Create the Device Data [Half-cut Specification] 3.3. Verify the Non-contact Surface Detector (NSD) Measurement Data [Half-cut Specification] 3.4. Use the Non-contact Surface Detector (NSD) Measure Function [Half-cut Specification] 3.5. Set the Process Control Table [Half-cut Specification] 3.6. Interpret the Cleaning Data [Half-cut Specification] 3.7. Interpret the Usage of Sub Index Data [Half-cut Specification] 4.1. Execute the Chopper Cut Setup (CCS) [Half-cut Specification] 4.2. Execute the Chopper Cut Setup Count Change Screen [Half-cut Specification] 4.3. Interpret the Chopper Cut Setup Count Change Screen [Half-cut Specification] 4.4. Interpret the Chopper Cut Setup Ref Adjustment [Half-cut Specification] 4.5. Execute the Chopper Cut Setup Kerf Adjustment [Half-cut Specification]	Item	Date	Trainee	Trainer
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Related Errors [Half-cut Specification]				
Related Errors [Half-cut Specification]				

5.5. Interpret the Recovery Operations for FO	UP
Related Errors [Half-cut Specification]	

Course composition, intended trainees and course objective

Course Name		Intended Trainees	Course Objective	
Operation	Operation 1	 who has no experience of operating the machine 	To enable trainees to understand the terms necessary for operating the machine and to process products by calling up the data set in the machine	
	Operation 2	 who has already completed the "Operation 1" course (or has equivalent operation skills) who conducts data and function settings of the machine 	To enable trainees to create the data and set the data and functions for operating the machine	
Mainte- nance	Mainte- nance 1	 who has already completed the "Operation 2" course (or has equivalent operation skills) who conducts periodic maintenance of the machine 	To enable trainees to safely and precisely perform the periodic maintenance and consumable parts replacement described in the Maintenance Manual of the machine	
	Mainte- nance 2	 who has already completed the "Maintenance 1" course (or has equivalent maintenance skills) who conducts maintenance works which are not described in the Maintenance Manual of the machine 	To enable trainees to conduct maintenance works which are not described in the machine Maintenance Manual (only the items that can be executed without any special tools or access to the internal Maker Data)	